# FSV530AF

# **Schottky Barrier Rectifier**

#### **Features**

- Low Forward Voltage Drop: 0.54 V Maximum at 5 A, T<sub>A</sub> = 25°C
- Ultra Thin Profile Maximum Height of 1.0 mm
- High Surge Capacity
- UL Flammability 94V-0 Classification
- MSL 1
- Green Mold Compound
- These Devices are Pb-Free, Halogen Free Free and are RoHS Compliant

### **Specifications**

## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{RRM}$	Recurrent Peak Reverse Voltage	30	V
V <sub>RMS</sub>	RMS Reverse Voltage	21	V
V <sub>R</sub>	DC Blocking Voltage	30	V
I <sub>F(AV)</sub>	Average Forward Current	5	Α
I <sub>FSM</sub>	Peak Forward Surge Current: 8.3 ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	100	А
TJ	Operating Junction Temperature Range	-55 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



## ON Semiconductor®

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#### **Schottky Barrier Rectifier**



DO-214AD (SMAF) CASE 403AD

#### **MARKING DIAGRAM**



Band Indicates Cathode

\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Data Code (Year & Week) FSV530AF = Specific Device Code

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

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#### FSV530AF

## THERMAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted) (Note 1)

Symbol	Characteristic	Value	Unit
$\Psi_{JL}$	Typical Thermal Characteristics, Junction-to-Lead (Note 2)	15	°C/W
$R_{\theta JA}$	Typical Thermal Resistance, Junction-to-Ambient	120	°C/W

<sup>1.</sup> Per JESD51–3 recommended thermal test board. Device mounted on FR-4 PCB, board size = 76.2 mm x 114.3 mm.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 5 A	-	-	0.54	V
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 30 V	-	-	100	μΑ
Trr	Reverse Recovery Time	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1 A, I <sub>rr</sub> = 0.25 A	-	15.72	-	ns
CJ	Junction Capacitance	V <sub>R</sub> = 0 V, f = 1 MHz	-	159	_	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **ORDERING INFORMATION**

Part Number	Top Mark	Package	Shipping <sup>†</sup>
FSV530AF	FSV530AF	DO-214AD (SMAF) (Pb-Free/Halogen Free)	10000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>2.</sup> Thermocouple soldered at cathode lead.

## FSV530AF

## **TYPICAL PERFORMANCE CHARACTERISTICS**

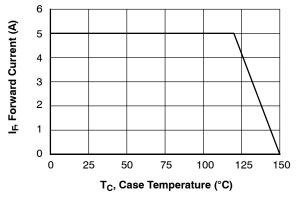


Figure 1. Forward Current Derating Curve

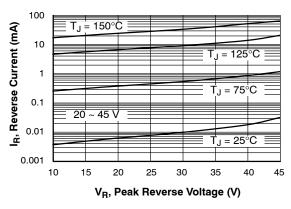


Figure 2. Typical Reverse Characteristics

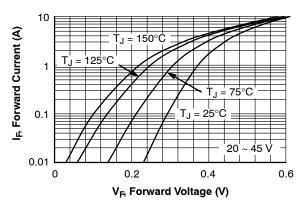


Figure 3. Typical Forward Characteristics

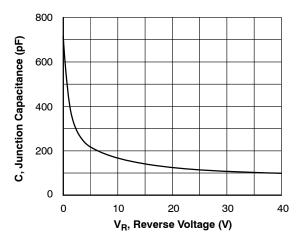


Figure 4. Typical Junction Capacitance



**CATHODE IDENTIFIER** 

// 0.05 C



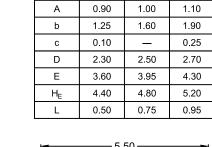
В

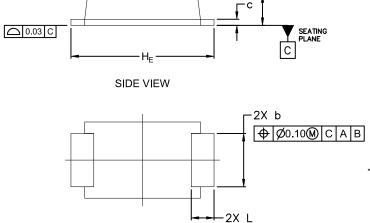
**DATE 14 JUL 2020** 



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009. CONTROLLING DIMENSION: MILLIMETERS DIMENSIONS D & E ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.

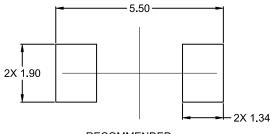
	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
Α	0.90	1.00	1.10
b	1.25	1.60	1.90
С	0.10	_	0.25
D	2.30	2.50	2.70
Е	3.60	3.95	4.30
HE	4.40	4.80	5.20
L	0.50	0.75	0.95





TOP VIEW

**BOTTOM VIEW** 



#### RECOMMENDED MOUNTING FOOTPRINT\*

For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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